DISCRETE SEMICONDUCTORS

DATA SHEET

BF994SN-channel dual-gate MOS-FET

Product specification

July 1993



N-channel dual-gate MOS-FET

BF994S

FEATURES

• Protected against excessive input voltage surges by integrated back-to-back diodes between gates and source.

APPLICATIONS

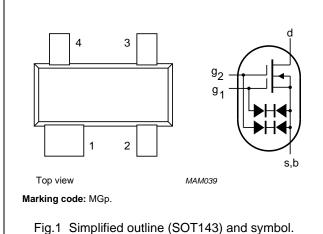
- VHF applications such as:
 - VHF television tuners
 - Professional communication equipment.

PINNING

PIN	SYMBOL	DESCRIPTION
1	s, b	source
2	d	drain
3	g ₂	gate 2
4	g 1	gate 1

DESCRIPTION

Depletion type field-effect transistor in a plastic SOT143 microminiature package with interconnected source and substrate.



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _{DS}	drain-source voltage		_	20	V
I_D	drain current		-	30	mA
P _{tot}	total power dissipation	up to T _{amb} = 60 °C	_	200	mW
Tj	junction temperature		_	150	°C
Y _{fs}	transfer admittance	$f = 1 \text{ kHz}; I_D = 10 \text{ mA}; V_{DS} = 15 \text{ V}; V_{G2-S} = 4 \text{ V}$	18	_	mS
C _{ig1-s}	input capacitance at gate 1	$f = 1 \text{ MHz}; I_D = 10 \text{ mA}; V_{DS} = 15 \text{ V}; V_{G2-S} = 4 \text{ V}$	2.5	3	pF
C _{rs}	feedback capacitance	$f = 1 \text{ MHz}; I_D = 10 \text{ mA}; V_{DS} = 15 \text{ V}; V_{G2-S} = 4 \text{ V}$	25	_	fF
F	noise figure	$f = 200 \text{ MHz}; G_S = 2 \text{ mS}; B_S = B_{Sopt}; I_D = 10 \text{ mA}; V_{DS} = 15 \text{ V}; V_{G2-S} = 4 \text{ V}$	1	_	dB

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LIMITING VALUES

In according with the Absolute Maximum Rating System (IEC 134).

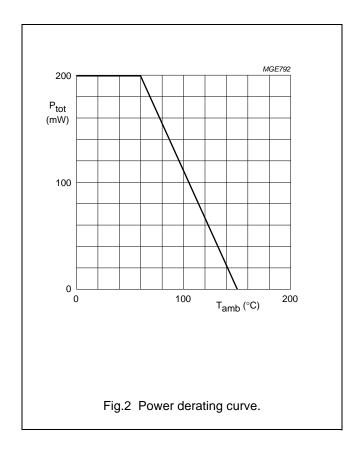
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DS}	drain-source voltage		_	20	V
I _D	drain current (DC)		_	30	mA
I _{D(AV)}	average drain current		_	30	mA
I _{G1-S}	gate 1-source current		_	±10	mA
I _{G2-S}	gate 2-source current		-	±10	mA
P _{tot}	total power dissipation	up to T _{amb} = 60 °C; note 1	_	200	mW
T _{stg}	storage temperature range		-65	+150	°C
Tj	junction temperature		_	150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient	in free air; note 1	460	K/W	

Note to the Limiting values and the Thermal characteristics

1. Device mounted on a ceramic substrate of $8 \times 10 \times 0.7$ mm.



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STATIC CHARACTERISTICS

 $T_j = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS		MAX.	UNIT
I _{G1-SS}	gate 1 cut-off currents	$V_{G1-S} = \pm 5 \text{ V}; V_{G2-S} = V_{DS} = 0$	_	±50	nA
I _{G2-SS}	gate 2 cut-off currents	$V_{G2-S} = \pm 5 \text{ V}; V_{G1-S} = V_{DS} = 0$	_	±50	nA
V _{(BR)G1-SS}	gate 1-source breakdown voltage	$I_{G1-SS} = \pm 10 \text{ mA}; V_{G2-S} = V_{DS} = 0$	±6	±20	٧
V _{(BR)G2-SS}	gate 2-source breakdown voltage	$I_{G2-SS} = \pm 10 \text{ mA}; V_{G1-S} = V_{DS} = 0$	±6	±20	٧
I _{DSS}	drain-source cut-off voltage	$V_{DS} = 15 \text{ V}; V_{G1-S} = 0; V_{G2-S} = 4 \text{ V}$	4	20	mA
V _{(P)G1-S}	gate 1-source cut-off voltage	$I_D = 20 \mu A; V_{DS} = 15 V; V_{G2-S} = 4 V$	_	-2.5	٧
V _{(P)G2-S}	gate 2-source cut-off voltage	$I_D = 20 \mu A; V_{DS} = 15 V; V_{G1-S} = 0$	_	-2	٧

DYNAMIC CHARACTERISTICS

Measuring conditions (common source): I_D = 10 mA; V_{DS} = 15 V; V_{G2-S} = 4 V; T_{amb} = 25 °C.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Y _{fs}	transfer admittance	f = 1 kHz	15	18	_	mS
C _{ig1-s}	input capacitance at gate 1	f = 1 MHz	_	2.5	3	pF
C _{ig2-s}	input capacitance at gate 2	f = 1 MHz	_	1.2	_	pF
C _{rs}	feedback capacitance	f = 1 MHz	_	25	_	fF
Cos	output capacitance	f = 1 MHz	_	1	_	pF
F	noise figure	$f = 200 \text{ MHz}; G_S = 2 \text{ mS}; B_S = B_{Sopt}$	_	1	_	dB
Gp	power gain	$f = 200 \text{ MHz}; G_S = 2 \text{ mS}; B_S = B_{Sopt};$	_	25	_	dB
		$G_L = 0.5 \text{ mS}; B_L = B_{Lopt}$				

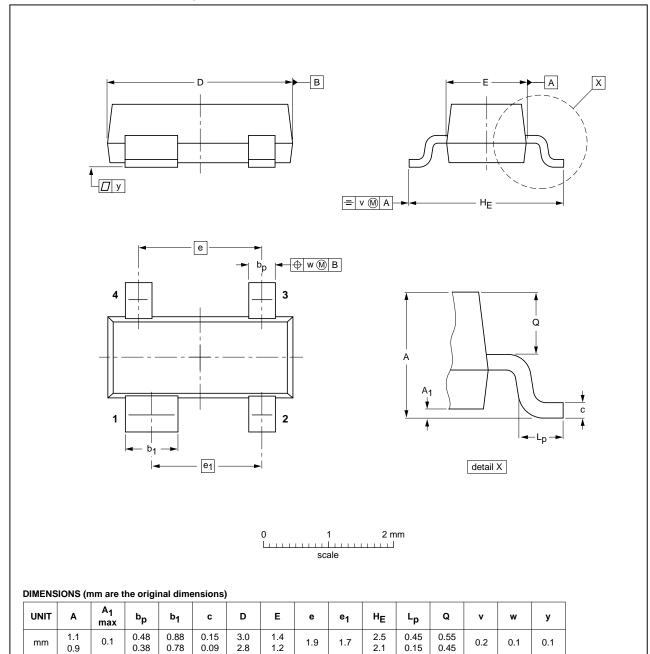
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PACKAGE OUTLINE

Plastic surface-mounted package; 4 leads

SOT143B



OUTLINE	REFERENCES			EUROPEAN ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT143B						04-11-16 06-03-16

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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